



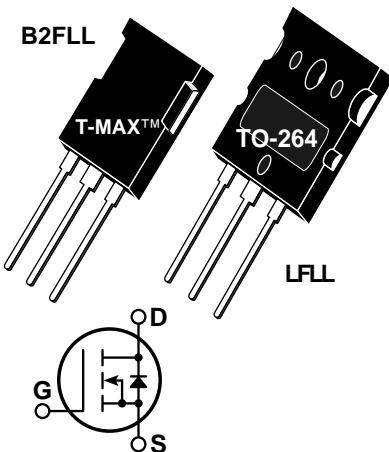
APT30M36B2FLL APT30M36LFLL 300V 84A 0.036Ω

POWER MOS 7™

FREDFET

Power MOS 7™ is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7™ by significantly lowering $R_{DS(ON)}$ and Q_g . Power MOS 7™ combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.

- Lower Input Capacitance
- Increased Power Dissipation
- Lower Miller Capacitance
- Easier To Drive
- Lower Gate Charge, Q_g
- Popular T-MAX™ or TO-264 Package
- FAST RECOVERY BODY DIODE



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT30M36	UNIT
V_{DSS}	Drain-Source Voltage	300	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	84	Amps
I_{DM}	Pulsed Drain Current ①	336	
V_{GS}	Gate-Source Voltage Continuous	± 30	Volts
V_{GSM}	Gate-Source Voltage Transient	± 40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	568	Watts
	Linear Derating Factor	4.54	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ① (Repetitive and Non-Repetitive)	84	Amps
E_{AR}	Repetitive Avalanche Energy ①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ④	2500	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$)	300			Volts
$I_{D(on)}$	On State Drain Current ② ($V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10\text{V}$)	84			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② ($V_{GS} = 10\text{V}$, $0.5 I_{D(\text{Cont.})}$)			0.036	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = V_{DSS}$, $V_{GS} = 0\text{V}$)			250	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 0.8 V_{DSS}$, $V_{GS} = 0\text{V}$, $T_C = 125^\circ\text{C}$)			1000	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30\text{V}$, $V_{DS} = 0\text{V}$)			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 2.5\text{mA}$)	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

USA	405 S.W. Columbia Street	Bend, Oregon 97702-1035	Phone: (541) 382-8028	FAX: (541) 388-0364
EUROPE	Chemin de Magret	F-33700 Merignac - France	Phone: (33) 5 57 92 15 15	FAX: (33) 5 56 47 97 61

DYNAMIC CHARACTERISTICS

APT30M36 B2FLL - LFLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		6540		pF
C_{oss}	Output Capacitance			1564		
C_{rss}	Reverse Transfer Capacitance			74		
Q_g	Total Gate Charge ③	$V_{GS} = 10V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D[\text{Cont.}] @ 25^\circ C$		122		nC
Q_{gs}	Gate-Source Charge			33		
Q_{gd}	Gate-Drain ("Miller") Charge			47		
$t_d(\text{on})$	Turn-on Delay Time	$V_{GS} = 15V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D[\text{Cont.}] @ 25^\circ C$		14		ns
t_r	Rise Time			19		
$t_d(\text{off})$	Turn-off Delay Time			30		
t_f	Fall Time	$R_G = 0.6\Omega$		5		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I_S	Continuous Source Current (Body Diode)			84	Amps
I_{SM}	Pulsed Source Current ① (Body Diode)			336	
V_{SD}	Diode Forward Voltage ② ($V_{GS} = 0V$, $I_S = -I_D[\text{Cont.}]$)			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑤			8	V/ns
t_{rr}	Reverse Recovery Time ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_J = 25^\circ C$		240	ns
		$T_J = 125^\circ C$		500	
Q_{rr}	Reverse Recovery Charge ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_J = 25^\circ C$		1.1	μC
		$T_J = 125^\circ C$		5.2	
I_{RRM}	Peak Recovery Current ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_J = 25^\circ C$		12	Amps
		$T_J = 125^\circ C$		22	

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.22	$^\circ C/W$
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

③ See MIL-STD-750 Method 3471

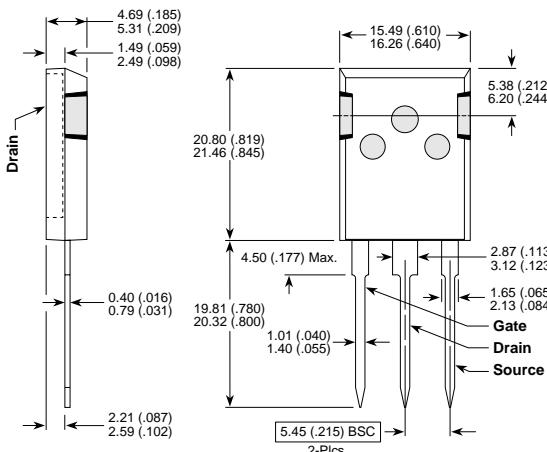
② Pulse Test: Pulse width < 380 μs , Duty Cycle < 2%

④ Starting $T_J = +25^\circ C$, $L = 0.71mH$, $R_G = 25\Omega$, Peak $I_L = 84A$

⑤ dv/dt numbers reflect the limitations of the test circuit rather than the device itself. $I_S \leq -I_D[\text{Cont.}]$ $dv/dt \leq 700A/\mu s$ $V_R \leq V_{DSS}$ $T_J \leq 150^\circ C$

APT Reserves the right to change, without notice, the specifications and information contained herein.

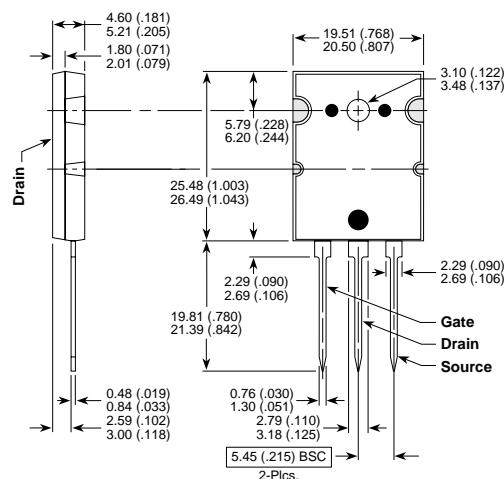
T-MAX™ (B2) Package Outline



These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

TO-264 (L) Package Outline



Dimensions in Millimeters and (Inches)